

ACPM-7371

UMTS 4x4 Power Amplifier (880-915MHz)



Data Sheet

Description

The ACPM-7371, a Wide-band Code Division Multiple Access(WCDMA) Power Amplifier (PA), is a fully matched 10-pin surface mount module developed for WCDMA handset applications. This power amplifier module is developed to cover 880-915MHz bandwidth. The ACPM-7371 meets the stringent WCDMA linearity requirements for output power of up to 28dBm. The ACPM-7371 is also developed to meet HSDPA specs up to 27.5dBm.

The ACPM-7371 is designed to enhance the efficiency at low and medium output power range by using 3-mode control scheme with 2 mode control pins. This provides extended talk time.

The ACPM-7371 is self contained, incorporating 50Ω input and output matching networks.

Features

- Excellent Linearity
- Low quiescent current
- High Efficiency
- 10-pin surface mounting package (4mmx4mmx1.1mm typ)
- Internal 50Ω matching networks for both RF input and output
- RoHS Compliant

Applications

- WCDMA Handset (HSDPA)

Order information

| Part Number | No. of Devices | Container |
|---------------|----------------|------------------|
| ACPM-7371-TR1 | 1000 | 7" Tape and Reel |
| ACPM-7371-BLK | 100 | BULK |

Functional Block Diagram

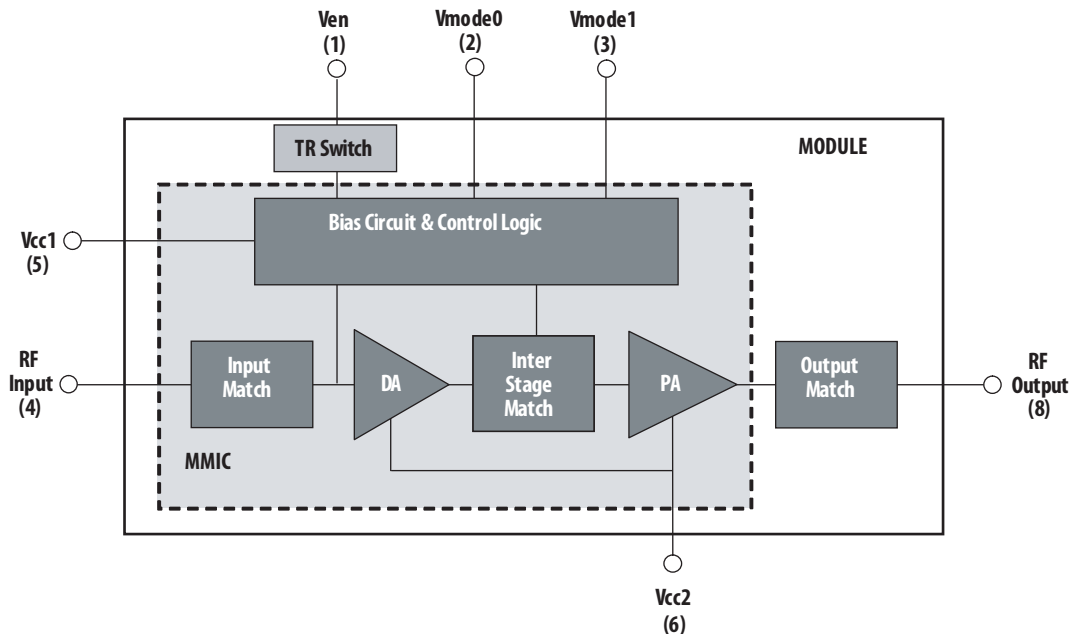


Table 1. Absolute Maximum Ratings

No damage assuming only one parameter is set at limit at a time with all other parameters set at or below typical value. Operation of any single parameter outside these conditions with the remaining parameters set at or below typical values may result in permanent damage

| Parameter | Min | TYP | Max | Unit | Associated Pins |
|----------------------|-----|-----|------|------|-----------------|
| RF Input Power | – | – | 10.0 | dBm | RFin |
| DC Supply Voltage | 0 | 3.4 | 5.0 | V | Vcc1, Vcc2 |
| Enable Voltage | 0 | 2.6 | 3.3 | V | Ven |
| Mode Control Voltage | 0 | 1.9 | 3.3 | V | Vmode0, Vmode 1 |
| Storage Temperature | -55 | – | +125 | °C | |

Table 2. Recommended Operating Condition

| Parameter | Min | Nominal | Max | Unit | |
|--|-------------|----------|------------|------------|-----|
| DC Supply Voltage | 3.2 | 3.4 | 4.2 | V | |
| Enable Voltage (Ven) | LOW HIGH | 0 1.9 | 0.5 2.6 | 0.5 2.9 | V |
| Mode Control Voltage (Vmode0, Vmode1) | LOW HIGH | 0 1.8 | 0 1.9 | 0.5 2.9 | V |
| Operating Frequency | | 880 | | 915 | MHz |
| Ambient Temperature | | -20 | 25 | 90 | °C |

Table 3. Power Range Truth Table

| Power Mode | Ven | Vmode0 | Vmode1 | Range |
|-----------------|------|--------|--------|-----------------|
| High Power Mode | High | Low | Low | ~ 28dBm (WCMDA) |
| Mid Power Mode | High | High | Low | ~ 16dBm |
| Low Power Mode | High | High | High | ~ 8dBm |
| Shut Down Mode | Low | – | – | – |

Table 4. Electrical Characteristics for WCDMA Mode

Vcc=3.4V, Ven=2.6V, Vmode0 and Vmode1= 0V or 1.9V, T=25°C, Zin/Zout=50Ω

Signal Configuration: 3GPP Uplink DPCCCH + 1DPDCH

| Characteristics | | Condition | Min. | Typ. | Max. | Unit |
|----------------------------------|-------------------------------|--|------|------|-------|--------|
| Operating Frequency Range | | | 880 | – | 915 | MHz |
| Gain | | High Power Mode, Pout=28.0 dBm | 23.5 | 26.5 | | dB |
| | | Mid Power Mode, Pout=16.0 dBm | 12.5 | 17 | | dB |
| | | Low Power Mode, Pout=8.0 dBm | 11.5 | 16 | | dB |
| Power Added Efficiency | | High Power Mode, Pout=28.0 dBm | 35.3 | 40.0 | | % |
| | | Mid Power Mode, Pout=16.0 dBm | 10.4 | 14.3 | | % |
| | | Low Power Mode, Pout=8.0 dBm | 3.3 | 5.2 | | % |
| Total Supply Current | | High Power Mode, Pout=28.0 dBm | | 463 | 535 | mA |
| | | Mid Power Mode, Pout=16.0 dBm | | 80 | 110 | mA |
| | | Low Power Mode, Pout=8.0 dBm | | 35 | 55 | mA |
| Quiescent Current | | High Power Mode | | 96 | 120 | mA |
| | | Mid Power Mode | | 18 | 24 | mA |
| | | Low Power Mode | | 13 | 18 | mA |
| Enable Current | | High Power Mode | | 0.18 | 1 | mA |
| | | Mid Power Mode | | 0.18 | 1 | mA |
| | | Low Power Mode | | 0.18 | 1 | mA |
| Control Current | | Mid Power Mode (Imode0) | | 0.4 | 1 | mA |
| | | Low Power Mode (Imode1) | | 0.18 | 1 | mA |
| | | Low Power Mode (Imode0) | | 0.4 | 1 | mA |
| Total Current in Power-down mode | | Ven=0V | | 0.2 | 5 | μA |
| Adjacent Channel Leakage Ratio | 5 MHz offset 10 MHz offset | High Power Mode, Pout=28.0 dBm | | -41 | -36 | dBc |
| | | | | -54 | -46 | |
| | 5 MHz offset 10 MHz offset | Mid Power Mode, Pout=16.0 dBm | | -48 | -36 | dBc |
| | | | | -61 | -46 | |
| | 5 MHz offset 10 MHz offset | Low Power Mode, Pout=8.0 dBm | | -40 | -36 | dBc |
| | | | | -56 | -46 | |
| Harmonic Suppression | 2fo | High Power Mode, Pout=28.0 dBm | | | -30 | dBc |
| | 3fo | | | | -45 | |
| Input VSWR | VSWR | | | | 2.5:1 | |
| Stability (Spurious Output) | | VSWR 5:1, All phase | | | -60 | dBc |
| Noise Power in Rx Band | | High Power Mode, Pout=28.0 dBm | | -132 | -130 | dBm/Hz |
| Phase Discontinuity | | low power mode <--> mid power mode, at Pout=8dBm | | | 10 | deg |
| | | mid power mode <--> high power mode, at Pout=16dBm | | | 30 | deg |
| Ruggedness | | Pout<28.0dBm, Pin<10dBm, All phase High Power Mode | | | 10:1 | VSWR |

Table 5. Electrical Characteristics for HSDPA Mode

V_{cc}=3.4V, V_{en}=2.6V, V_{mode0} and V_{mode1}=0V or 1.9V, T=25°C, Z_{in}/Z_{out}=50Ω

Signal configuration: DPCCH/DPDCH=12/15, HS-DPCCH/DPDCH=15/15

| Characteristics | | Condition | Min. | Typ. | Max. | Unit |
|--------------------------------|-------------------------------|--|------|------|------|------|
| Operating Frequency Range | | | 880 | – | 915 | MHz |
| Gain | | High Power Mode, P _{out} = 27.5 dBm | 23.5 | 26 | | dB |
| | | Mid Power Mode, P _{out} = 16.0 dBm | 12.5 | 17 | | dB |
| | | Low Power Mode, P _{out} = 8.0 dBm | 11.5 | 16 | | dB |
| Power Added Efficiency | | High Power Mode, P _{out} = 27.5 dBm | 33.7 | 36.7 | | % |
| | | Mid Power Mode, P _{out} = 16.0 dBm | 10.4 | 14.7 | | % |
| | | Low Power Mode, P _{out} = 8.0 dBm | 3.3 | 5.2 | | % |
| Total Supply Current | | High Power Mode, P _{out} = 27.5 dBm | | 450 | 490 | mA |
| | | Mid Power Mode, P _{out} = 16.0 dBm | | 78 | 110 | mA |
| | | Low Power Mode, P _{out} = 8.0 dBm | | 35 | 55 | mA |
| Adjacent Channel Leakage Ratio | 5 MHz offset 10 MHz offset | High Power Mode, P _{out} = 27.5 dBm | – | -40 | -36 | dBc |
| | | | | -52 | -46 | dBc |
| | 5 MHz offset 10 MHz offset | Mid Power Mode, P _{out} = 16.0 dBm | – | -44 | -36 | dBc |
| | | | | -58 | -46 | dBc |
| | 5 MHz offset 10 MHz offset | Low Power Mode, P _{out} = 8.0 dBm | – | -40 | -36 | dBc |
| | | | | -56 | -46 | dBc |

Characteristics Data

WCDMA, $V_{cc}=3.4V$, $V_{en}=2.6V$, V_{mode0} and $V_{mode1}=0V$ or $1.9V$, $T=25^\circ$, $Z_{in}/Z_{out}=50\Omega$

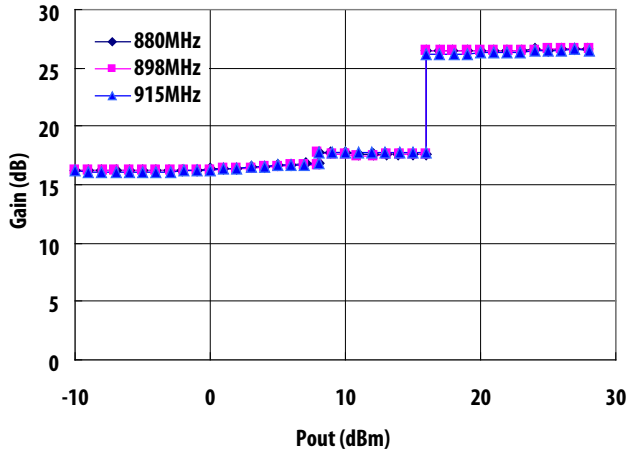


Figure 1. Gain vs. Output Power

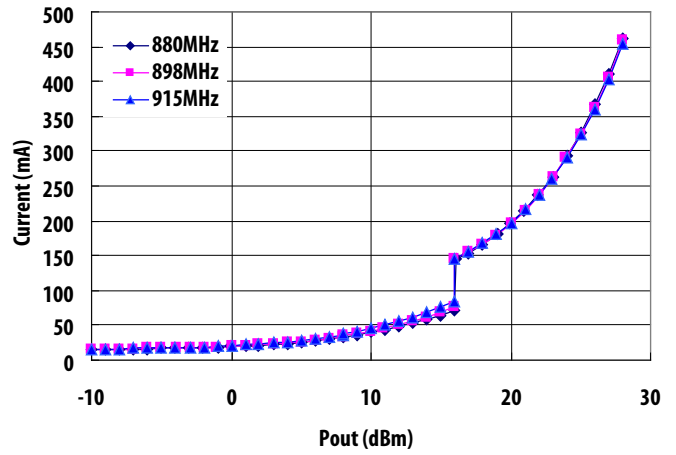


Figure 2. Total Current vs. Output Power

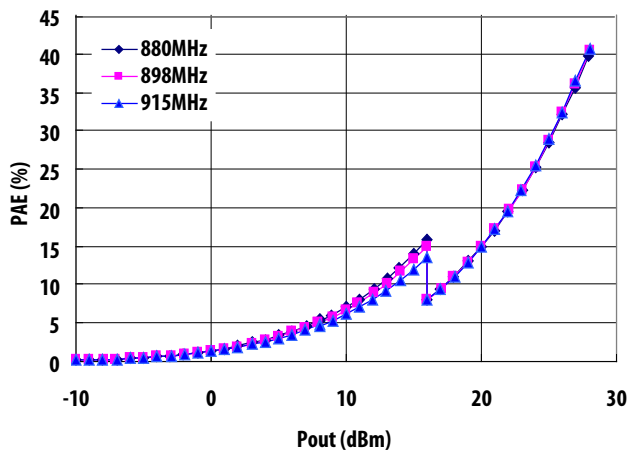


Figure 3. Power Added Efficiency vs. Output Power

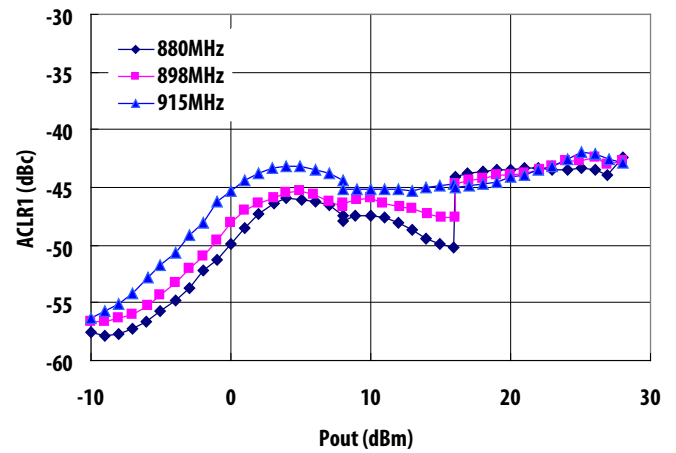


Figure 4. Adjacent Channel Leakage Ratio 1 vs. Output Power

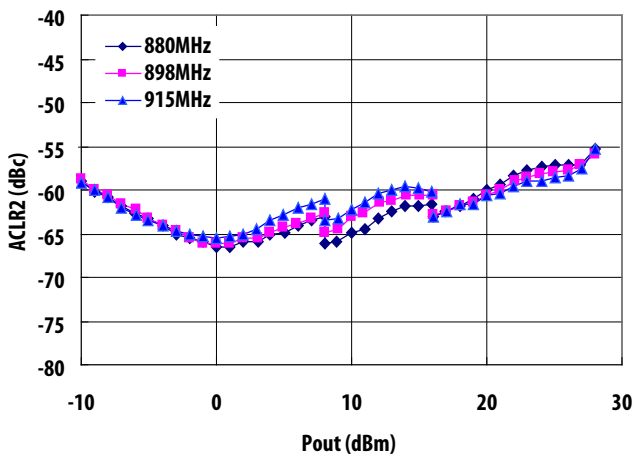


Figure 5. Adjacent Channel Leakage Ratio 2 vs. Output Power

Evaluation Board Description

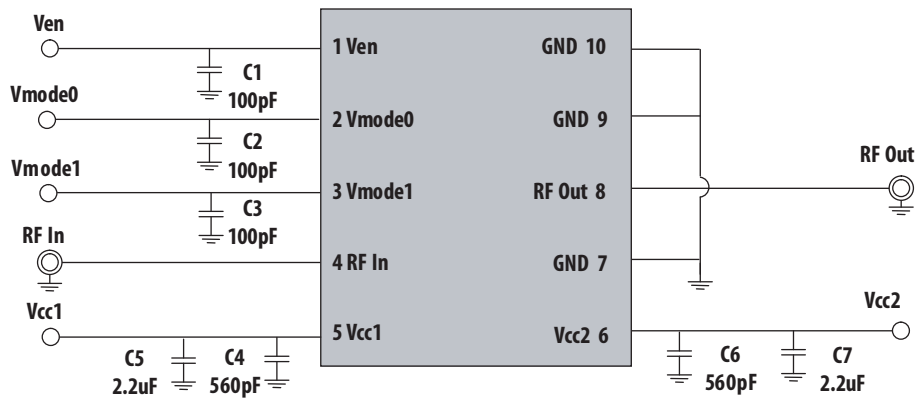


Figure 6. Evaluation Board Schematic

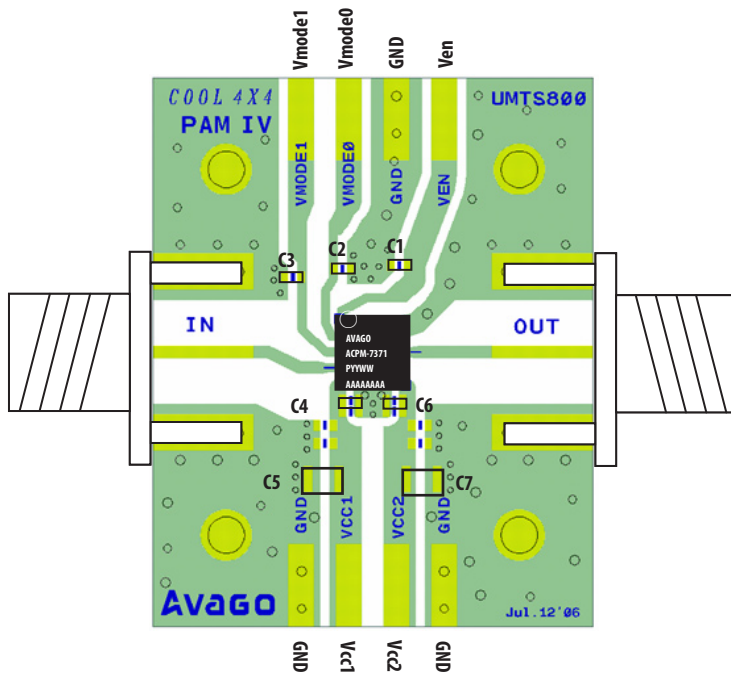


Figure 7. Evaluation Board Assembly Diagram

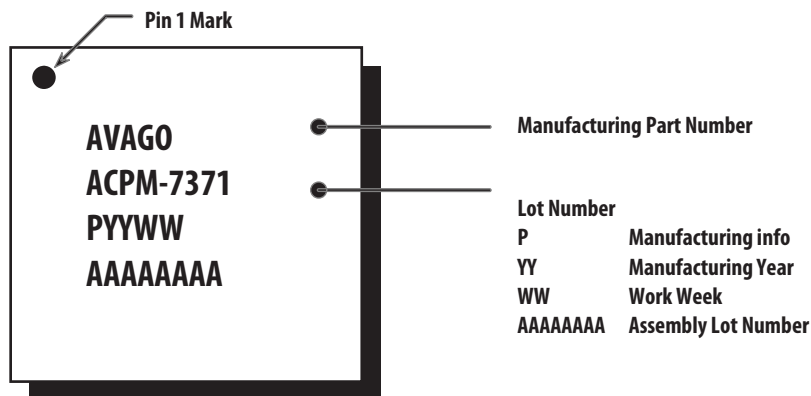


Figure 8. Marking Specifications

Package Dimensions and Pin Descriptions

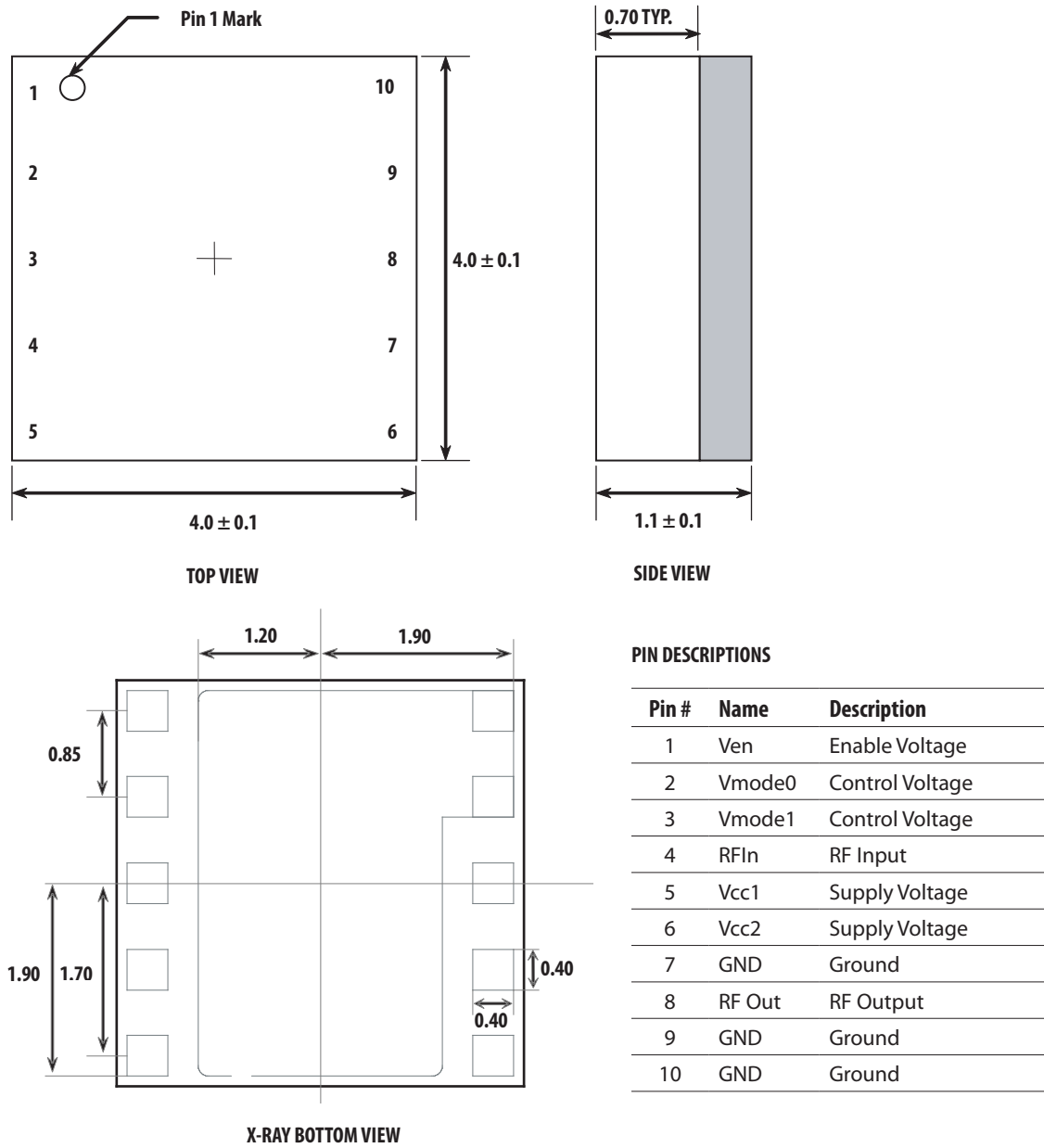


Figure 9. Package Dimensional Drawing and Pin Descriptions (All dimensions are in millimeters)

CoolPAM

Avago Technologies' CoolPAM is stage-bypass PA technology which saves more power compared with conventional PA. With this technology, the ACPM-7371 has very low quiescent current and efficiencies at low and medium output power ranges are very high.

Incorporation of bias circuit

The ACPM-7371 has internal bias circuit, which removes the need for external constant voltage source (LDO). PA on/off is controlled by Ven. This is digitally control pin.

3-mode power control with two mode control pins

The ACPM-7371 supports three power modes (low power mode/mid power mode/high power mode) with two mode control pins (Vmode0 and Vmode1). This control scheme enables the ACPM-7371 to save more power, which accordingly gives extended talk time.

PDF (probability density function) in below figure showing distribution of output power of mobile in real field gives motivation for stage-bypass PA. Output power is less than 16dBm for most of operating time (during talking), so it is important to save power consumption at low and medium output power ranges.

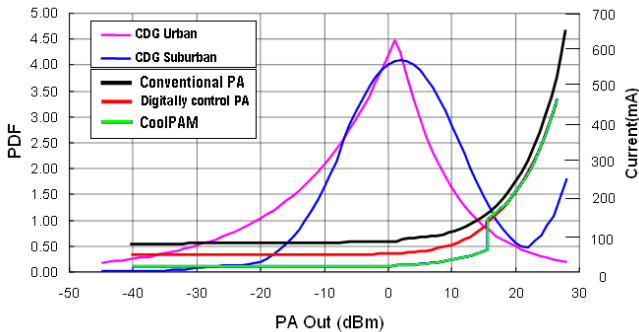


Figure 10. PDF and Current

Average current & Talk time

Average current consumed by PA can be calculated by summing up current at each output power weighted with probability. So it is expressed with integration of multiplication of current and probability at each output power.

$$\text{Average current} = \int (\text{PDF} \times \text{Current}) dp$$

Talk time is extended more as average current consumption is lowered.

Mode control pins

Vmode0 and Vmode1 are digitally controlled pins and they control operating mode of PA and truth table is summarized in Table 3. These pins do not require constant voltage for interface, and 1.9V is recommend at Vmode0 and Vmode1 pins.

Application on mobile board

Below figure shows one application example on mobile. C4 and C5 should be placed nearby pin1 and pin10. Transmission line length after PA output should be minimized to reduce conduction loss. When output voltage of mode control pins at base-band chipset is 2.6V, series resistor of 2Kohm is recommended for Vmode0 and 4.7kohm for Vmode1.

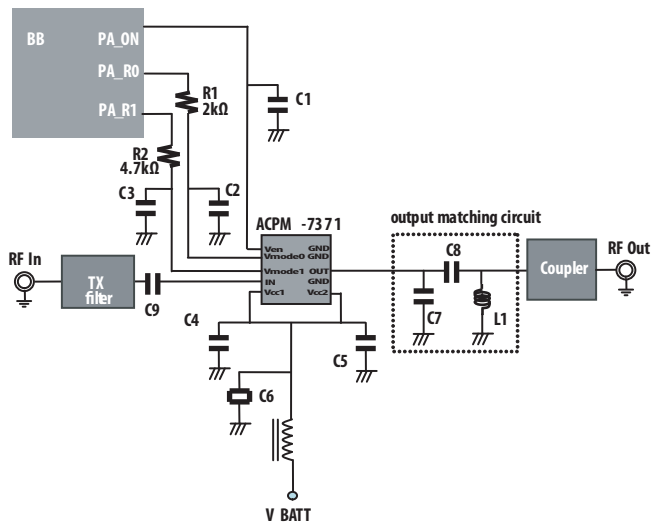


Figure 11. ACPM-7371 Application Example

PCB Design Guidelines

The recommended ACPM-7371 PCB land pattern is shown in Figure 12 and Figure 13. The substrate is coated with solder mask between the I/O and conductive paddle to protect the gold pads from short circuit that is caused by solder bleeding/bridging.

Stencil Design Guidelines

A properly designed solder screen or stencil is required to ensure optimum amount of solder paste is deposited onto the PCB pads. The recommended stencil layout is shown in Figure 14. Reducing the stencil opening can potentially generate more voids. On the other hand, stencil openings larger than 100% will lead to excessive solder paste smear or bridging across the I/O pads or conductive paddle to adjacent I/O pads. Considering the fact that solder paste thickness will directly affect the quality of the solder joint, a good choice is to use laser cut stencil composed of 0.10mm (4mils) or 0.127mm (5mils) thick stainless steel which is capable of producing the required fine stencil outline.

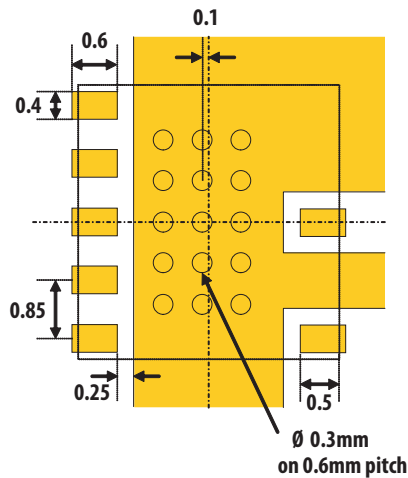


Figure 12. Metallization

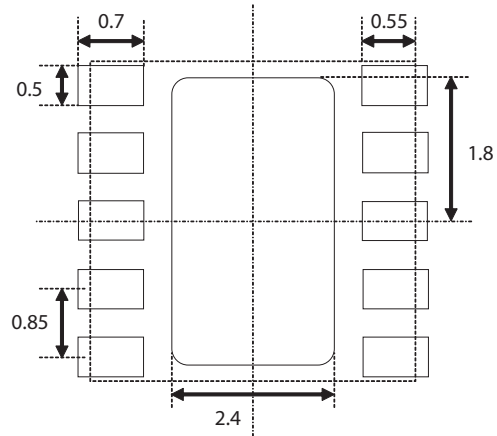


Figure 13. Solder Mask Opening

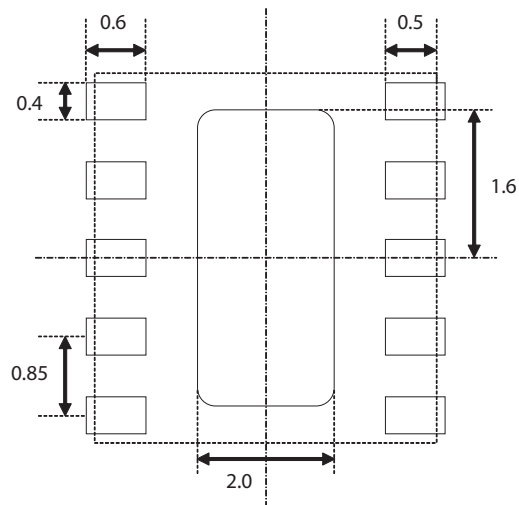


Figure 14. Solder Paste Stencil Aperture

Tape and Reel Information

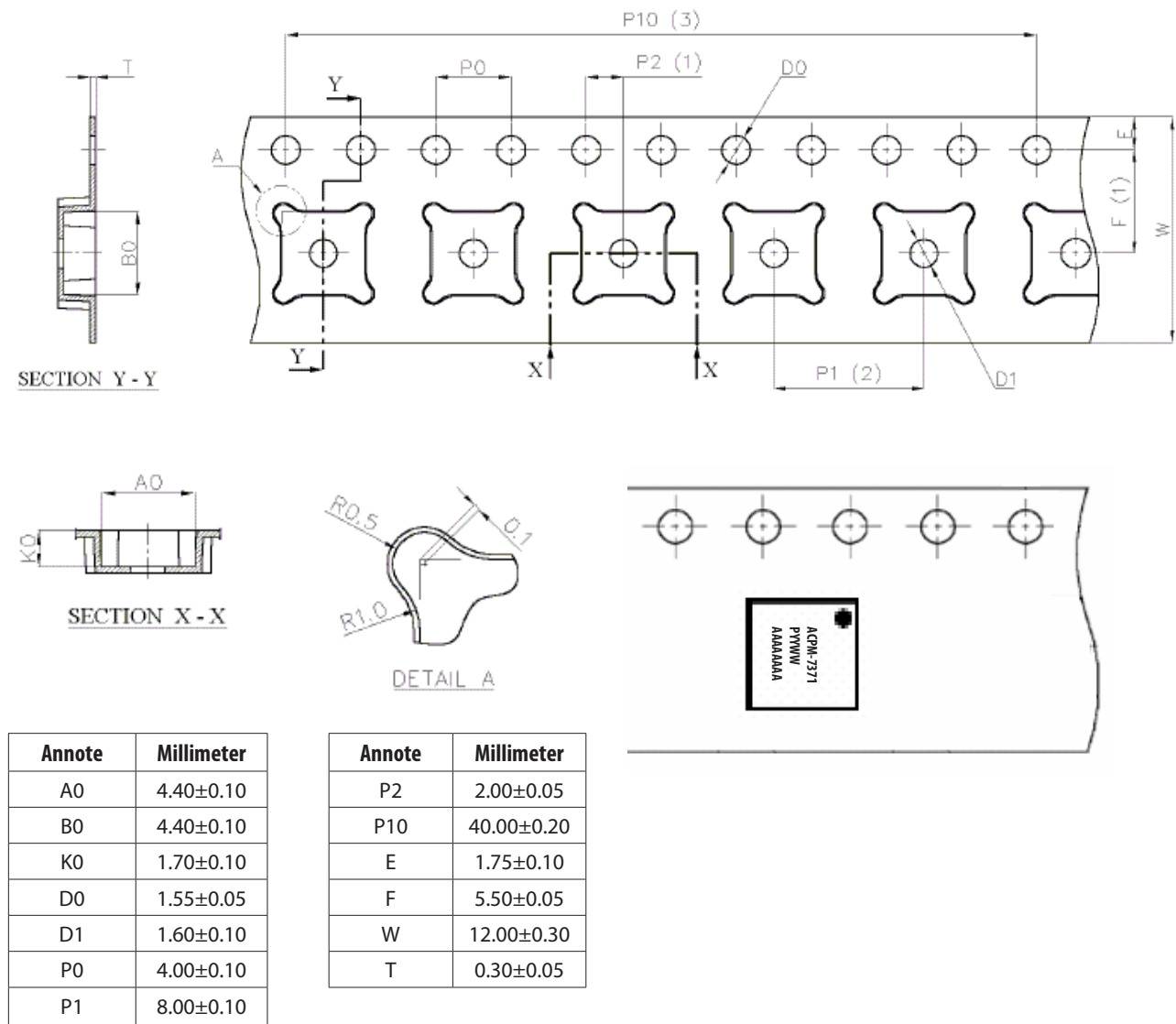


Figure 15. Tape and Reel Format – 4 mm x 4 mm.

Reel Drawing

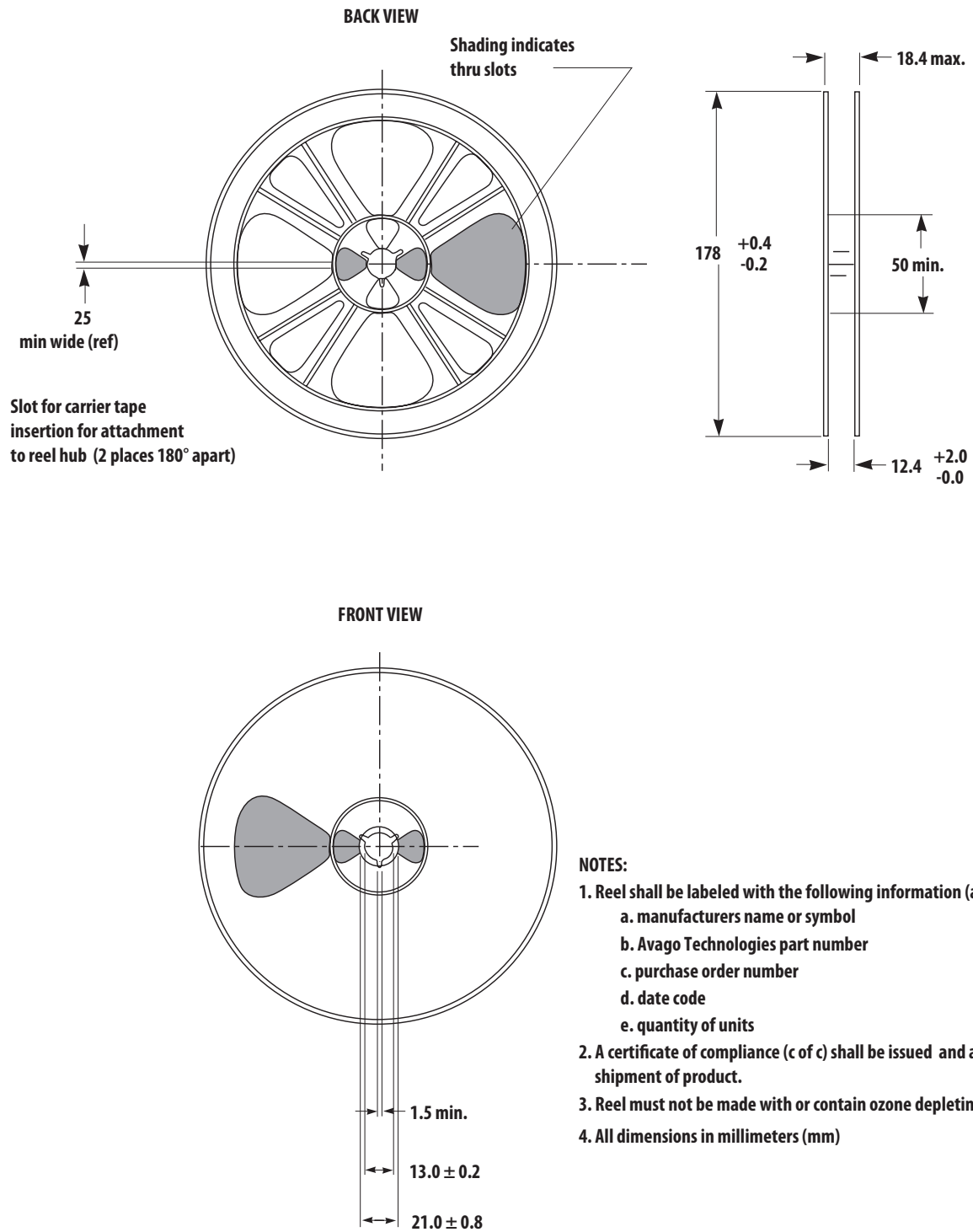


Figure 16. Plastic Reel Format (all dimensions are in millimeters)

Handling and Storage

ESD (Electrostatic Discharge)

Electrostatic discharge occurs naturally in the environment. With the increase in voltage potential, the outlet of neutralization or discharge will be sought. If the acquired discharge route is through a semiconductor device, destructive damage will result.

ESD countermeasure methods should be developed and used to control potential ESD damage during handling in a factory environment at each manufacturing site.

MSL (Moisture Sensitivity Level)

Plastic encapsulated surface mount package is sensitive to damage induced by absorbed moisture and temperature.

Avago Technologies follows JEDEC Standard J-STD 020B. Each component and package type is classified for moisture sensitivity by soaking a known dry package at

various temperatures and relative humidity, and times. After soak, the components are subjected to three consecutive simulated reflows.

The out of bag exposure time maximum limits are determined by the classification test describe below which corresponds to a MSL classification level 6 to 1 according to the JEDEC standard IPC/JEDEC J-STD-020B and J-STD-033.

ACPM-7381 is MSL3. Thus, according to the J-STD-033 p.11 the maximum Manufacturers Exposure Time (MET) for this part is 168 hours. After this time period, the part would need to be removed from the reel, de-taped and then re-baked. MSL classification reflow temperature for the ACPM-7381 is targeted at 260° +0/-5°C. Figure 17 and Table 7 show typical SMT profile for maximum temperature of 260 +0/-5°C.

Table 6. Moisture Classification Level and Floor Life

| MSL Level | Floor Life (out of bag) at factory ambient $\leq 30^{\circ}\text{C}/60\% \text{RH}$ or as stated |
|-----------|--|
| 1 | Unlimited at $\leq 30^{\circ}\text{C}/85\% \text{RH}$ |
| 2 | 1 year |
| 2a | 4 weeks |
| 3 | 168 hours |
| 4 | 72 hours |
| 5 | 48 hours |
| 5a | 24 hours |
| 6 | Mandatory bake before use. After bake, must be reflowed within the time limit specified on the label |

Note :

1. The MSL Level is marked on the MSL Label on each shipping bag.

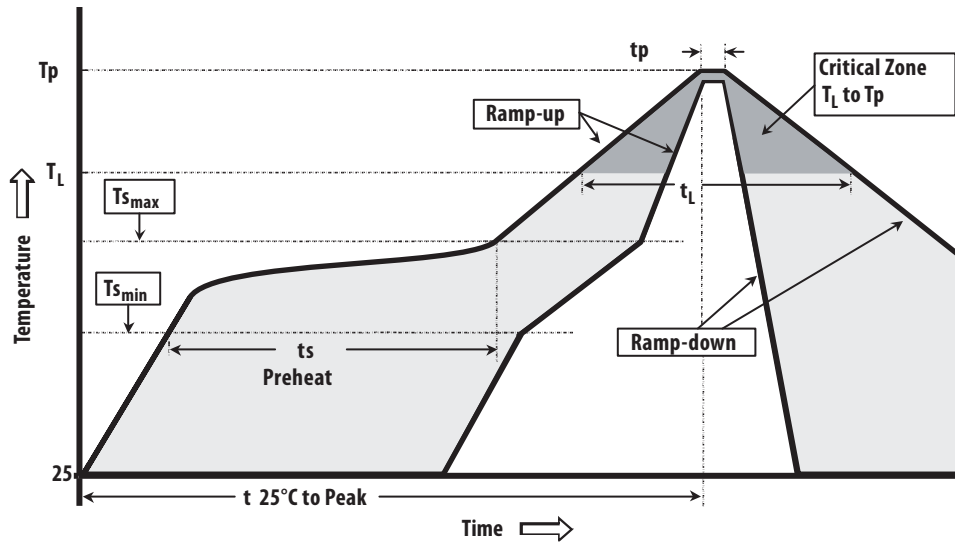


Figure 17. Typical SMT Reflow Profile for Maximum Temperature = 260 +0/-5°C

Table 7. Typical SMT Reflow Profile for Maximum Temperature = 260+0 / -5°C

| Profile Feature | Sn-Pb Solder | Pb-Free Solder |
|--|---------------|----------------|
| Average ramp-up rate (TL to TP) | 3°C/sec max | 3° C/sec max |
| Preheat | | |
| - Temperature Min (T _{min}) | 100°C | 150°C |
| - Temperature Max (T _{max}) | 150°C | 200°C |
| - Time (min to max) (t _s) | 60-120 sec | 60-180 sec |
| T _{max} to TL | | |
| - Ramp-up Rate | | 3° C /sec max |
| Time maintained above: | | |
| - Temperature (TL) | 183°C | 217°C |
| - Time (TL) | 60-150 sec | 60-150 sec |
| Peak temperature (T _p) | 240 +0/-5°C | 260 +0/-5°C |
| Time within 5°C of actual Peak Temperature (t _p) | 10-30 sec | 20-40 sec |
| Ramp-down Rate | 6° C /sec max | 6° C /sec max |
| Time 25°C to Peak Temperature | 6 min max. | 8 min max. |

Storage Condition

Packages described in this document must be stored in sealed moisture barrier, antistatic bags. Shelf life in a sealed moisture barrier bag is 12 months at <40°C and 90% relative humidity (RH) J-STD-033 p.7.

Out-of-Bag Time Duration

After unpacking the device must be soldered to the PCB within 168 hours as listed in the J-STD-020B p.11 with factory conditions <30°C and 60% RH.

Baking

It is not necessary to re-bake the part if both conditions (storage conditions and out-of-bag conditions) have been satisfied. Baking must be done if at least one of the conditions above have not been satisfied. The baking conditions are 125°C for 12 hours J-STD-033 p.8.

CAUTION

Tape and reel materials typically cannot be baked at the temperature described above. If out-of-bag exposure time is exceeded, parts must be baked for a longer time at low temperatures, or the parts must be de-reeled, de-taped, re-baked and then put back on tape and reel. (See moisture sensitive warning label on each shipping bag for information of baking).

Board Rework

Component Removal, Rework and Remount

If a component is to be removed from the board, it is recommended that localized heating be used and the maximum body temperatures of any surface mount component on the board not exceed 200°C. This method will minimize moisture related component damage. If any component temperature exceeds 200°C, the board must be baked dry per 4-2 prior to rework and/or component removal. Component temperatures shall be measured at the top center of the package body. Any SMD packages that have not exceeded their floor life can be exposed to a maximum body temperature as high as their specified maximum reflow temperature.

Removal for Failure Analysis

Not following the above requirements may cause moisture/reflow damage that could hinder or completely prevent the determination of the original failure mechanism.

Baking of Populated Boards

Some SMD packages and board materials are not able to withstand long duration bakes at 125°C. Examples of this are some FR-4 materials, which cannot withstand a 24 hr bake at 125°C. Batteries and electrolytic capacitors are also temperature sensitive. With component and board temperature restrictions in mind, choose a bake temperature from Table 4-1 in J-STD 033; then determine the appropriate bake duration based on the component to be removed. For additional considerations see IPC-7711 and IPC-7721.

Derating due to Factory Environmental Conditions

Factory floor life exposures for SMD packages removed from the dry bags will be a function of the ambient environmental conditions. A safe, yet conservative, handling approach is to expose the SMD packages only up to the maximum time limits for each moisture sensitivity level as shown in Table 6. This approach, however, does not work if the factory humidity or temperature is greater than the testing conditions of 30°/60% RH. A solution for addressing this problem is to derate the exposure times based on the knowledge of moisture diffusion in the component package materials ref. JESD22-A120). Recommended equivalent total floor life exposures can be estimated for a range of humidities and temperatures based on the nominal plastic thickness for each device.

Table 8 lists equivalent derated floor lives for humidities ranging from 20-90% RH for three temperature, 20°, 25°, and 30°C.

This table is applicable to SMDs molded with novolac, biphenyl or multifunctional epoxy mold compounds. The following assumptions were used in calculating Table 9:

1. Activation Energy for diffusion = 0.35eV (smallest known value).
2. For ≤60% RH, use Diffusivity = $0.121 \exp(-0.35\text{eV}/kT)$ mm²/s (this used smallest known Diffusivity @ 30°C).
3. For >60% RH, use Diffusivity = $1.320 \exp(-0.35\text{eV}/kT)$ mm²/s (this used largest known Diffusivity @ 30°C).

Table 8. Recommended Equivalent Total Floor Life (days) @ 20°C, 25 °C & 30 °C

For ICs with Novolac, Biphenyl and Multifunctional Epoxies.
(Reflow at same temperature at which the component was classified)

Maximum Percent Relative Humidity

| Package Type and Body Thickness | Moisture Sensitivity Level | Moisture Sensitivity | | | | | | | | | | | | |
|--|---|----------------------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| | | 5% | 10% | 20% | 30% | 40% | 50% | 60% | 70% | 80% | 90% | | | |
| Body Thickness ≥3.1 mm Including PQFPs >84 pin, PLCCs (square) All MQFPs or All BGAs ≥1 mm | Level 2a | ∞ | ∞ | ∞ | 60 | 41 | 33 | 28 | 10 | 7 | 6 | 30° | | |
| | | ∞ | ∞ | ∞ | 78 | 53 | 42 | 36 | 14 | 10 | 8 | 25° | | |
| | | ∞ | ∞ | ∞ | 103 | 69 | 57 | 47 | 19 | 13 | 10 | 20° | | |
| | Level 3 | ∞ | ∞ | 10 | 9 | 8 | 7 | 7 | 5 | 4 | 4 | 30° | | |
| | | ∞ | ∞ | 13 | 11 | 10 | 9 | 9 | 7 | 6 | 5 | 25° | | |
| | | ∞ | ∞ | 17 | 14 | 13 | 12 | 12 | 10 | 8 | 7 | 20° | | |
| | Level 4 | ∞ | 5 | 4 | 4 | 4 | 3 | 3 | 3 | 2 | 2 | 30° | | |
| | | ∞ | 6 | 5 | 5 | 5 | 5 | 4 | 3 | 3 | 3 | 25° | | |
| | | ∞ | 8 | 7 | 7 | 7 | 7 | 6 | 5 | 4 | 4 | 20° | | |
| | Level 5 | ∞ | 4 | 3 | 3 | 2 | 2 | 2 | 2 | 1 | 1 | 30° | | |
| | | ∞ | 5 | 5 | 4 | 4 | 3 | 3 | 2 | 2 | 2 | 25° | | |
| | | ∞ | 7 | 7 | 6 | 5 | 5 | 4 | 3 | 2 | 3 | 20° | | |
| | Level 5a | ∞ | 2 | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 30° | | |
| | | ∞ | 3 | 2 | 2 | 2 | 2 | 2 | 1 | 1 | 1 | 25° | | |
| | | ∞ | 5 | 4 | 3 | 3 | 3 | 2 | 2 | 2 | 2 | 20° | | |
| | Body 2.1 mm ≤ Thickness <3.1 mm including PLCCs (rectangular) 18-32 pin SOICs (wide body) SOICs ≥20 pins, PQFPs ≤80 pins | Level 2a | ∞ | ∞ | ∞ | ∞ | 86 | 39 | 28 | 4 | 3 | 2 | 30° | |
| | | | ∞ | ∞ | ∞ | ∞ | 148 | 51 | 37 | 6 | 4 | 3 | 25° | |
| | | | ∞ | ∞ | ∞ | ∞ | ∞ | 69 | 49 | 8 | 5 | 4 | 20° | |
| Level 3 | | ∞ | ∞ | 19 | 12 | 9 | 8 | 7 | 3 | 2 | 2 | 30° | | |
| | | ∞ | ∞ | 25 | 15 | 12 | 10 | 9 | 5 | 3 | 3 | 25° | | |
| | | ∞ | ∞ | 32 | 19 | 15 | 13 | 12 | 7 | 5 | 4 | 20° | | |
| Level 4 | | ∞ | 7 | 5 | 4 | 4 | 3 | 3 | 2 | 2 | 1 | 30° | | |
| | | ∞ | 9 | 7 | 5 | 5 | 4 | 4 | 3 | 2 | 2 | 25° | | |
| | | ∞ | 11 | 9 | 7 | 6 | 6 | 5 | 4 | 3 | 3 | 20° | | |
| Level 5 | | ∞ | 4 | 3 | 3 | 2 | 2 | 2 | 1 | 1 | 1 | 30° | | |
| | | ∞ | 5 | 4 | 3 | 3 | 3 | 3 | 2 | 1 | 1 | 25° | | |
| | | ∞ | 6 | 5 | 5 | 4 | 4 | 4 | 3 | 3 | 2 | 20° | | |
| Level 5a | | ∞ | 2 | 1 | 1 | 1 | 1 | 1 | 1 | 0.5 | 0.5 | 30° | | |
| | | ∞ | 2 | 2 | 2 | 2 | 2 | 2 | 1 | 1 | 1 | 25° | | |
| | | ∞ | 3 | 2 | 2 | 2 | 2 | 2 | 2 | 2 | 1 | 20° | | |
| Body Thickness <2.1 mm including SOICs <18 pin All TQFPs, TSOPs or All BGAs <1 mm body thickness | | Level 2a | ∞ | ∞ | ∞ | ∞ | ∞ | ∞ | 28 | 1 | 1 | 1 | 30° | |
| | | | ∞ | ∞ | ∞ | ∞ | ∞ | ∞ | ∞ | ∞ | 2 | 1 | 1 | 25° |
| | | | ∞ | ∞ | ∞ | ∞ | ∞ | ∞ | ∞ | ∞ | 2 | 2 | 1 | 20° |
| | Level 3 | ∞ | ∞ | ∞ | ∞ | ∞ | 11 | 7 | 1 | 1 | 1 | 30° | | |
| | | ∞ | ∞ | ∞ | ∞ | ∞ | 14 | 10 | 2 | 1 | 1 | 25° | | |
| | | ∞ | ∞ | ∞ | ∞ | ∞ | 20 | 13 | 2 | 2 | 1 | 20° | | |
| | Level 4 | ∞ | ∞ | ∞ | 9 | 5 | 4 | 3 | 1 | 1 | 1 | 30° | | |
| | | ∞ | ∞ | ∞ | 12 | 7 | 5 | 4 | 2 | 1 | 1 | 25° | | |
| | | ∞ | ∞ | ∞ | 17 | 9 | 7 | 6 | 2 | 2 | 1 | 20° | | |
| | Level 5 | ∞ | ∞ | 13 | 5 | 3 | 2 | 2 | 1 | 1 | 1 | 30° | | |
| | | ∞ | ∞ | 18 | 6 | 4 | 3 | 3 | 2 | 1 | 1 | 25° | | |
| | | ∞ | ∞ | 26 | 8 | 6 | 5 | 4 | 2 | 2 | 1 | 20° | | |
| | Level 5a | ∞ | 10 | 3 | 2 | 1 | 1 | 1 | 1 | 1 | 0.5 | 30° | | |
| | | ∞ | 13 | 5 | 3 | 2 | 2 | 2 | 1 | 1 | 1 | 25° | | |
| | | ∞ | 18 | 6 | 4 | 3 | 2 | 2 | 2 | 2 | 1 | 20° | | |

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